



# Product Change Notification

## 112466 - 00

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**Americas Contact:** [asmo.pcn@intel.com](mailto:asmo.pcn@intel.com)

**Asia Pacific/PRC Contact:** [apacgccb@intel.com](mailto:apacgccb@intel.com)

**Europe Email:** [eccb@intel.com](mailto:eccb@intel.com)

**Japan Email:** [jccb.ijkk@intel.com](mailto:jccb.ijkk@intel.com)

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# Product Change Notification

**Change Notification #:** 112466 - 00  
**Change Title:** Intel® NUC Kit DC53427HY, Boxed & Bulk  
Intel® NUC Kit DC3217IYE, Boxed  
Intel® NUC Board D53427RK, Bulk  
PCN 112466-00, Product Design  
Remove LPC Header and Change  
Components  
**Date of Publication:** August 1, 2013

**Key Characteristics of the Change:**  
Product Design

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	<b>Aug 23, 2013</b>
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## Description of Change to the Customer:

Remove LPC (Low Pin Count) header on HYE and RKE and change components on HYE, IYE, and RKE to enhance the RTC (Real Time Clock) circuit.

## Customer Impact of Change and Recommended Action:

This change has been thoroughly evaluated to ensure that there are no quality, reliability or functional implications to our customers. Intel is not recommending additional qualification of these changes on platforms received from Intel.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

## Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change SA	Pre Change AA	Post Change SA	Post Change AA
BOXDC3217IYE	924222	G80097-104	G76540-203	G80097-105	G76540-204
BLKD53427RKE	927919	G87790-402	G87790-402	H10106-100	G87790-403
BOXDC53427HYE	927920	H10106-100	G87971-402	H10106-101	G87971-403
BLKDC53427HYE	930170	G87963-101	G87971-402	G87963-102	G87971-403

**PCN Revision History:**

**Date of Revision:**

August 1, 2013

**Revision Number:**

00

**Reason:**

Originally Published PCN